





APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-40 °C TO +125 °C	STORAGE TEMPERATURE RANGE	-10 °C TO +60°C <sup>(1)</sup>	
	VOLTAGE	 60 V AC/DC	STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 85% MAX	
	CURRENT	2 A		(NOT DEWED)	
SPECIFICATIONS					
ITEM		TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION					
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	x	x
MARKING		CONFIRMED VISUALLY.		x	x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE		1A DC.	10 mΩ MAX .	x	—
CONTACT RESISTANCE MILLIVOLT LEVEL METHOD		10 mV AC MAX, 0.1 mA(DC OR 1000Hz)	10 mΩ MAX .	x	—
INSULATION RESISTANCE		500 V DC.	100 MΩ MIN.	x	—
VOLTAGE PROOF		1000 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	x	—
MECHANICAL CHARACTERISTICS					
MECHANICAL OPERATION		30 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 20 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
VIBRATION		FREQUENCY 20 TO 200Hz (88m/s <sup>2</sup> ) SWEEP TIME 3min.(ROUND TRIP) AT 3h FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 7ΩMIN , 1μs MIN. ② CONTACT RESISTANCE: 20 mΩ MAX. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
SHOCK		981m/s <sup>2</sup> DURATION OF PULSE 6ms AT 3 TIMES FOR 6 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 7ΩMIN , 1μs MIN. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
LOCK STRENGTH		MEASURE BREAK STRENGTH OF THE LOCK BY PULLING THE CONNECTOR IN THE MATING DIRECTION.	① 100N MIN.	x	—
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)		EXPOSED AT 60 °C, 90 ~ 95 %, 96 h.	① CONTACT RESISTANCE: 20 mΩ MAX. ② INSULATION RESISTANCE:100 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
RAPID CHANGE OF TEMPERATURE		TEMPERATURE- 40 →ROOM TEMP →125°C→ ROOM TEMP TIME 30 → 5 → 30 → 5 min UNDER 1000 CYCLES.	① CONTACT RESISTANCE: 20 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
DRY HEAT		EXPOSED AT 140°C, 120 h.	① CONTACT RESISTANCE: 20 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
COLD		EXPOSED AT -40°C , 120 h.	① CONTACT RESISTANCE: 20 mΩ MAX. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
RESISTANCE TO SO <sub>2</sub> GAS		EXPOSED IN 25 PPM AT 75% MIN FOR 96h.	① CONTACT RESISTANCE: 20 mΩ MAX.	x	—
RESISTANCE TO SOLDERING HEAT		REFLOW TEMP. OVER 260°C , 10sec. PREHEAT 180°C MAX , 120sec.	NO PLATING PEELING OF THE TERMINALS, MELTINGS OF HOUSINGS.	x	—
SOLDERABILITY		SOLDERED AT SPECIFIED TEMPERATURE PROFILE.	A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	1	DIS-T-00006023	YH. MAMADA	HH. TSUKUMO	20200407
REMARK			APPROVED	AH. EDASHIGE	20190313
(NOTE1) "STORAGE" means a long-term storage state for the unused product before assembly to PCB.			CHECKED	YH. MAMADA	20190313
			DESIGNED	YONGMUN LEE	20190313
			DRAWN	MN. SATOH	20190313
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-368632-00-00
	SPECIFICATION SHEET		PART NO.	ZE05-20DP-2H	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL752-2106-0-00	 1/1